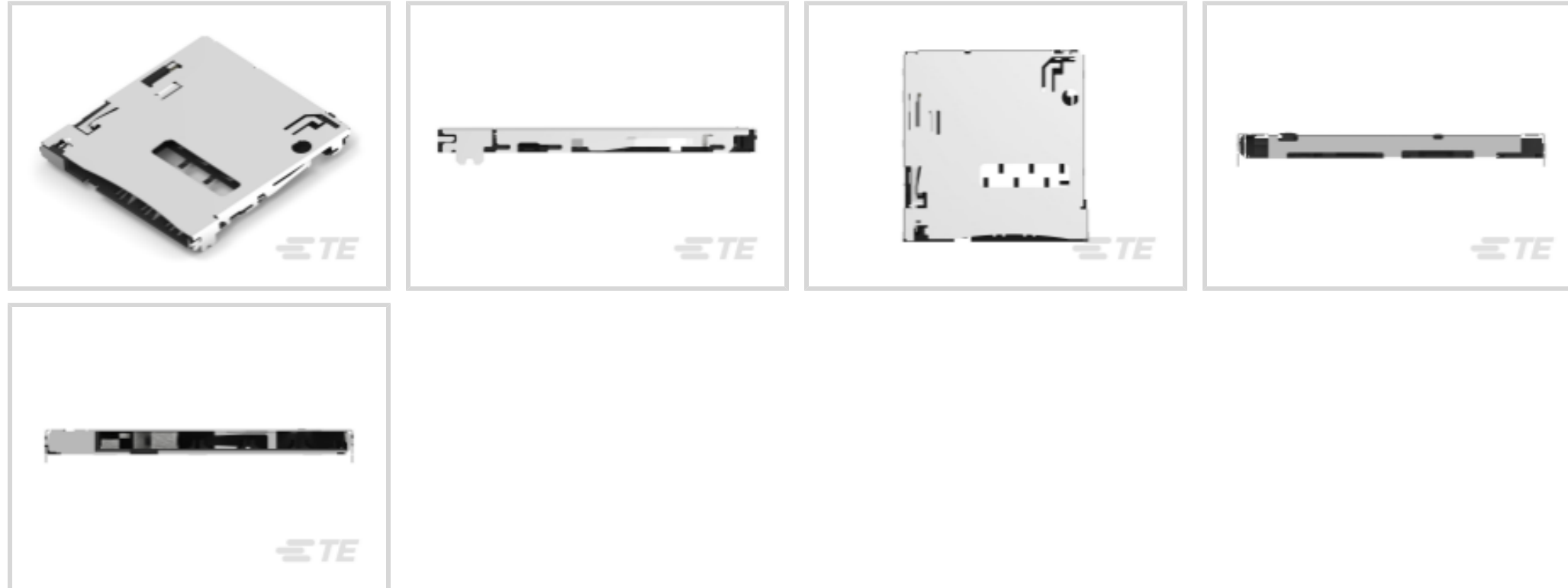




Connectors > PCB Connectors > Memory Card Connectors > SIM Card Connectors



Compatible Card: **SIM/SAM**
 Number of Positions: **6**
 Centerline (Pitch): **2.54 mm [.1 in]**
 Number of Loaded Positions: **6**
 Connector & Contact Terminates To: **Printed Circuit Board**

Features

Product Type Features

Compatible Card	SIM/SAM
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Number of Positions	6
Number of Loaded Positions	6

Contact Features

Contact Current Rating (Max)	.5 A
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Termination Features

Termination Method to Printed Circuit Board	Surface Mount
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Mechanical Attachment

Connector Mounting Type	Board Mount
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Housing Features

Centerline (Pitch)	2.54 mm[.1 in]
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Usage Conditions

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Operating Temperature Range	-30 – 85 °C[-22 – 185 °F]
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Operation/Application

Circuit Application	Signal
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

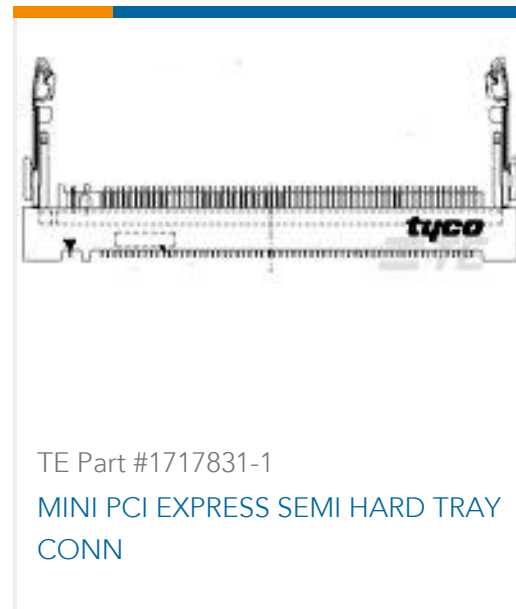
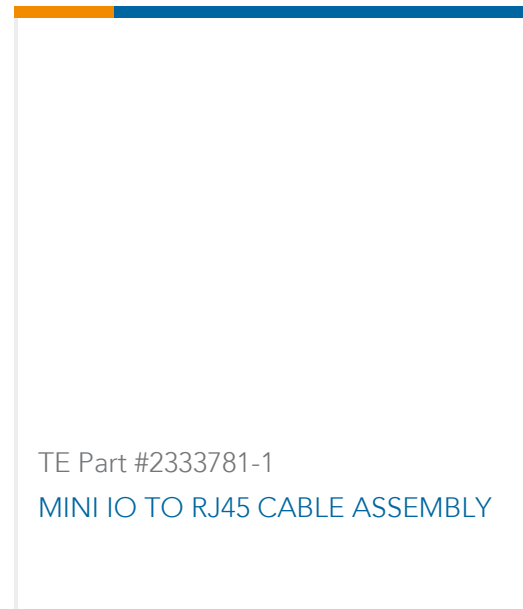
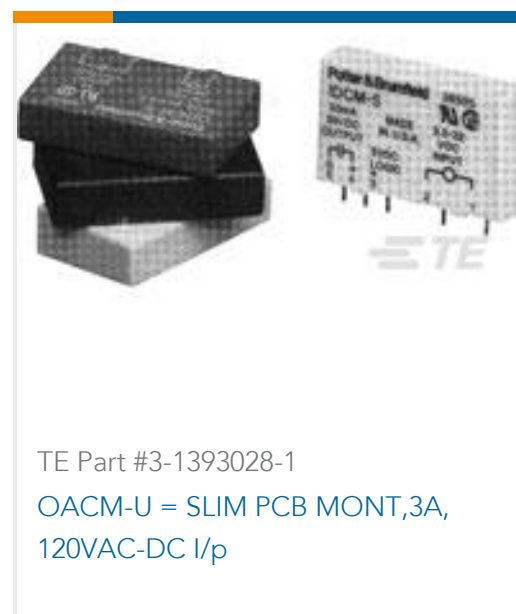
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

 <p>TE Part # 2201778-1 MICRO SD PUSH PUSH LOW PROFILE TYPE</p>	 <p>TE Part # 1554901-1 SHIELD FINGER 2011 EMBOSS PACKING</p>	 <p>TE Part # 2309923-2 BLOCK SIM CONNECTOR SIDE ENTRY</p>	 <p>TE Part # 2336582-1 PUSH-PUSH NANO SIM CONNECTOR</p>
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Customers Also Bought



Documents

Product Drawings

PUSH-PUSH MICRO SIM CONNECTOR

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2822541-1_C.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2822541-1_C.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2822541-1_C.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Product Specification

English

Product Environmental Compliance

TE Material Declaration

English